



# Samples Specifications

**Model No :** 5MM 圆头雾状红/纯绿共阴

**Spec No :** ATI-5RDRPGH-CC-L01

## Descriptions

- 5 mm LED

**Emitting Color:** Red/Green

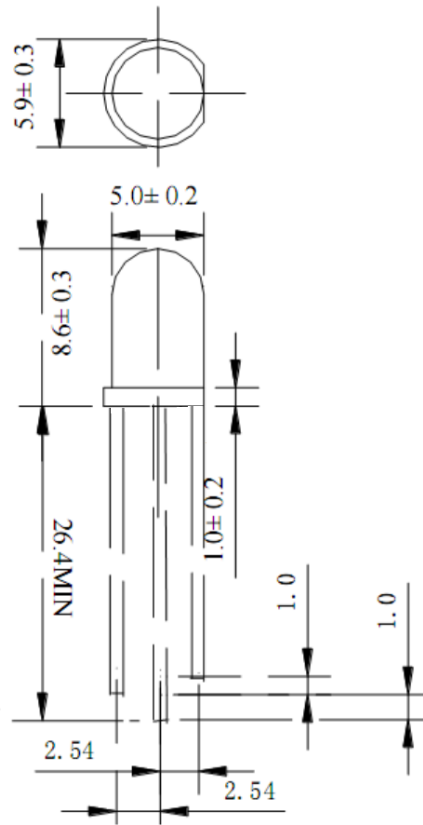
- Viewing Angle: 60°
- Lens: Diffused

Client Signature			Company Signature		
Approved	Acceptance	Stamp	sales	Approved	Creation
					ZRG





## Package Dimension:



G --R

## Notes:

1. All dimensions in mm tolerance is  $\pm 0.15\text{mm}$  unless otherwise noted
2. An epoxy meniscus may extend about 1.5mm down the leads
3. Burr around bottom of epoxy may be 0.5mm max.
4. Specifications are subject to change without notice



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## Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Absolute maximum Rating	Unit
Continuous Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	100	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	100	mW
Operating Temperature Range	Topr	-30 to +85	°C
Storage Temperature Range	Tstg	-40 to +100	°C
Lead Soldering Temperature [2mm From Body]	Tsld	260°C for 3Seconds	

## Electrical Optical Characteristics at Ta=25

Parameter	Symbol	Test Condition	Color	Min.	Type.	Max.	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20mA	Red	1.9	---	2.3	V
			Green	2.8	--	3.2	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5V		---	---	1	μA
Wavelength	LD	I <sub>F</sub> = 20mA	Red	620		630	nm
			Green	515		525	
illumination	IV	I <sub>F</sub> = 20mA	Red		2000		mcd
			Green		5000		
Viewing Angle	2θ <sub>1/2</sub>	I <sub>F</sub> = 20mA	---	---	60	----	deg

### Notes:

1)Tolerance of measurement of luminous intensity is ±15%.

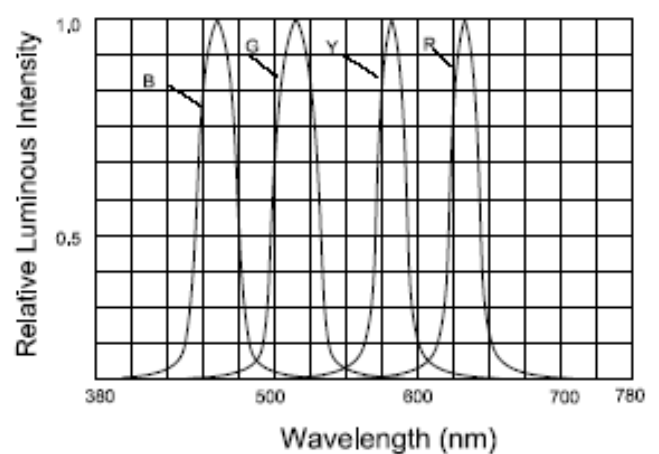
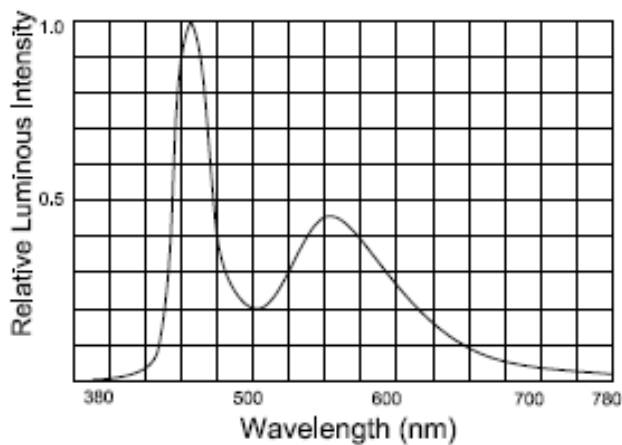
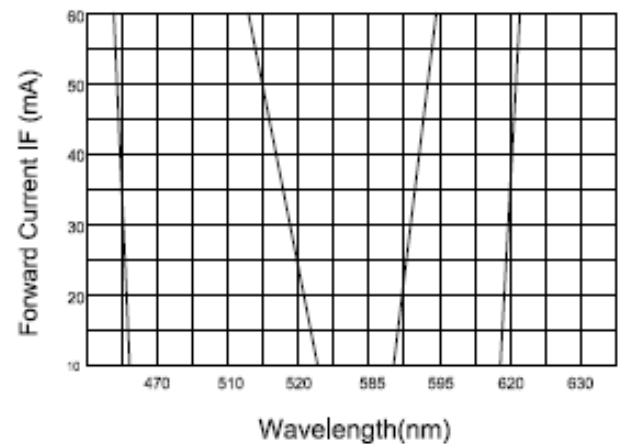
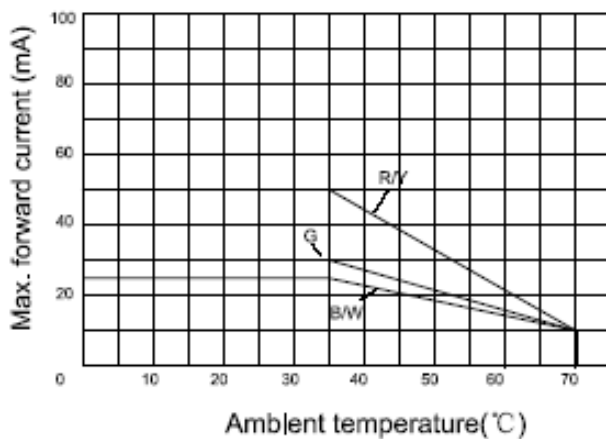
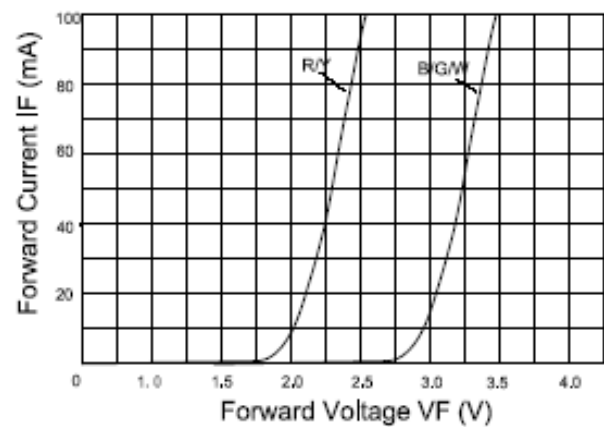
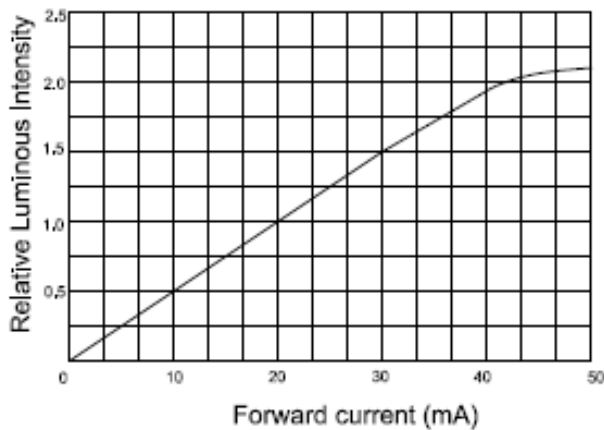
2)Tolerance of measurement of forward voltage is ±0.05 V.



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## ● Typical Electrical /Optical Characteristics Curves

(25°C Ambient Temperature Unless\_ Otherwise Noted)





## Jointing explanation

### lead-free solder

mode	fixed form
Hand soldering	1. Soldering time : 3 sec MAX. 2. Distance : 2mm MIN (from solder joint to case)
DIP soldering	1. Preheat temp : 100 °C MAX , 60 sec MAX. 2. Bath temp : 265 °C MAX. 3. Bath time : 5 sec MAX. 4. Distance : 3 mm MIN (From solder joint to case) 5. decrease temperature externally and compulsorily after dip soldering)
Reflow	NO

### Lamp wave soldering profile :

